

IR-E1 BGA REWORK STATION

Focused Infrared Precision, Zero Compromise.

OVERVIEW

The IR-E1 is a compact, precision-focused BGA rework system designed for reliable, cost-effective rework of small to medium PCB assemblies. Built around controlled infrared heating and manual placement, it delivers consistent results for everyday rework applications without unnecessary complexity.



KEY ADVANTAGES



FOCUSED INFRARED HEATING

- Visible, targeted focused IR heating directly to the component
- No damage to surrounding components
- Precise and adjustable energy for safe rework



PCB PREHEATER

- Protects components and PCBs from thermal shock
- Fast, even zonal PCB heating
- Reduces thermal gradients, warping, and board stress



THERMOACTIVE SOFTWARE

- Simple, intuitive interface for process control
- Automated temperature profiling and monitoring
- Ensures consistent, repeatable rework performance



SENSORS

- Non-contact infrared sensor for component temperature measurement
- Contact probe for accurate PCB temperature monitoring
- Enables independent control of component and PCB temperatures



HANDHELD VACUUM TOOL

- Manual component placement and removal
- Smooth, controlled handling of components
- Provides operator flexibility and precision

TECHNICAL SPECIFICATIONS

Max PCB Size: 12 x 18"/300 x 450mm

Max Component Size: 2.1 x 2.1"/55 x 55mm

Min Component Size: 01005

Component Removal: Manual Pick-Up System

Component Placement: Split Beam Prism Alignment/x50 Magnification

Placement Accuracy: Up to 10um

Top Heater Power: 150W Focused Infrared up to Ø70mm Spot

PCB Preheater Power: 2800W Medium-Wave IR (3 Zones)

PCB Preheater Heating Area Size: 14.1 x 9.4"/360 x 240mm

Component Temperature Sensing: Non-Contact IR Sensor

PCB Temperature Sensing: Contact Probe

Number of TC Channels: 4